

Additional Information





Accessories



Resources

Samples

Description

The 30R Series radial leaded device is designed to provide overcurrent protection for low voltage (≤30V) applications where space is not a concern and resettable protection is

Features & Benefits

- Cured, flame retardant epoxy polymer insulating material meets UL 94V-0 requirements
- Fast time-to-trip
- RoHS compliant, Lead-Free and Halogen-Free*

Applications

- USB hubs, ports and peripherals
- Computers & peripherals
- Motor protection
- General electronics
- Automotive applications

Agency Approvals

Agency	Agency File Number
c SN °us	E74889
\triangle	R72161784

Electrical Characteristics

			V	I P Maximum Time To Trip		Time To Trip	Resis	tance	Agency A	pprovals	
Part Number	(A)	(A)	V _{max} (Vdc)	(A)	typ. (W)	Current (A)	Time (Sec.)	R _{min} (Ω)	R _{1max} (Ω)	c '911 ' us	A
30R090U	0.90	1.80	30	40	0.6	4.50	5.90	0.070	0.220	Χ	Χ
30R110U	1.10	2.20	30	40	0.7	5.50	6.60	0.050	0.170	Χ	Χ
30R135U	1.35	2.70	30	40	0.8	6.75	7.30	0.040	0.130	Χ	Χ
30R160U	1.60	3.20	30	40	0.9	8.00	8.00	0.030	0.110	X	Χ
30R185U	1.85	3.70	30	40	1.0	9.25	8.70	0.030	0.090	X	Χ
30R250U	2.50	5.00	30	40	1.2	12.50	10.30	0.020	0.070	Χ	Χ
30R300U	3.00	6.00	30	40	2.0	15.00	10.80	0.020	0.080	Χ	Χ
30R400U	4.00	8.00	30	40	2.5	20.00	12.70	0.010	0.050	X	Χ
30R500U	5.00	10.00	30	40	3.0	25.00	14.50	0.010	0.050	Χ	Χ
30R600U	6.00	12.00	30	40	3.5	30.00	16.00	0.005	0.040	Χ	Χ
30R700U	7.00	14.00	30	40	3.8	35.00	17.50	0.005	0.030	Χ	Χ
30R800U	8.00	16.00	30	40	4.0	40.00	18.80	0.005	0.020	Χ	Χ
30R900U	9.00	18.00	30	40	4.2	40.00	20.00	0.005	0.020	X	X

Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.

- I hold = Hold current: maximum current device will pass without tripping in 20°C still air.

- $t_{trip} = Trip$ current: minimum current at which the device will trip in 20°C still air. $t_{trip} = Trip$ current: minimum current at which the device will trip in 20°C still air. $t_{trip} = Trip$ current: minimum current at which the device without damage at rated current (I max) $t_{trip} = Trip$ current: minimum current device can withstand without damage at rated voltage ($t_{trip} = t_{trip} = t_{trip$
- $\mathbf{P}_{\mathbf{d}}^{\text{max}}$ = Power dissipated from device when in the tripped state at 20°C still air.

- R min = Minimum resistance of device in initial (un-soldered) state.
- typ = Typical resistance of device in initial (un-soldered) state. R _{1max} = Maximum resistance of device at 20°C measured one hour after tripping.
- * Effective February 11, 2010 onward, all 600R PTC products will be manufactured Halogen Free (HF). Existing Non-Halogen Free 600R PTC products may continue to be sold, until supplies are depleted. This change will have no effect on 600R product specifications or performance.

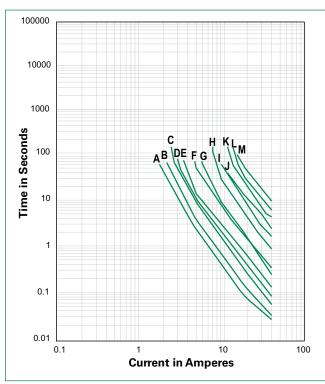
- Users shall independently assess the suitability of these devices for each of their applications
- Operation of these devices beyond the stated maximum ratings could result in damage to the devices and lead to electrical arcing and/or fire
- These devices are intended to protect against the effects of temporary over-current or over-temperature conditions and are not intended to perform as protective devices where such conditions are expected to be repetitive or prolonged in duration
- Exposure to silicon-based oils, solvents, electrolytes, acids, and similar materials can adversely affect the performance of these PPTC devices
- These devices undergo thermal expansion under fault conditions, and thus shall be provided with adequate space and be protected against mechanical stresses
- Circuits with inductance may generate a voltage (L di/dt) above the rated voltage of the PPTC device



Temperature Rerating

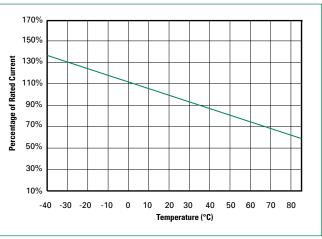
				Ambien	t Operation Tem	nerature					
					•	•	_		_		
	-40°C	-20°C	0°C	20°C	40°C	50°C	60°C	70°C	85°C		
Part Number		Hold Current (A)									
30R090U	1.31	1.17	1.04	0.90	0.75	0.69	0.61	0.55	0.47		
30R110U	1.60	1.43	1.27	1.10	0.91	0.85	0.75	0.67	0.57		
30R135U	1.96	1.76	1.55	1.35	1.12	1.04	0.92	0.82	0.70		
30R160U	2.32	2.08	1.84	1.60	1.33	1.23	1.09	0.98	0.83		
30R185U	2.68	2.41	2.13	1.85	1.54	1.42	1.26	1.13	0.96		
30R250U	3.63	3.25	2.88	2.50	2.08	1.93	1.70	1.53	1.30		
30R300U	4.35	3.90	3.45	3.00	2.49	2.31	2.04	1.83	1.56		
30R400U	5.80	5.20	4.60	4.00	3.32	3.08	2.72	2.44	2.08		
30R500U	7.25	6.50	5.75	5.00	4.15	3.85	3.40	3.05	2.60		
30R600U	8.70	7.80	6.90	6.00	4.98	4.62	4.08	3.66	3.12		
30R700U	10.15	9.10	8.05	7.00	5.81	5.39	4.76	4.27	3.64		
30R800U	11.60	10.40	9.20	8.00	6.64	6.16	5.44	4.88	4.16		
30R900U	13.05	11.70	10.35	9.00	7.47	6.93	6.12	5.49	4.68		

Average Time Current Curves



The average time current curves and Temperature Rerating curve performance is affected by a number or variables, and these curves provided as guidance only. Customer must verify the performance in their application.

Temperature Rerating Curve

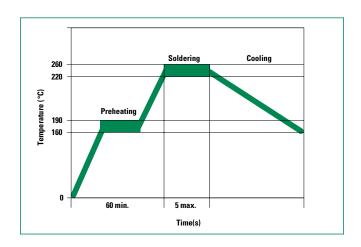


Note: Typical Temperature rerating curve, refer to table for derating data



Soldering Parameters - Wave Soldering

Pre-Heating Zone	Refer to the condition recommended by the flux manufacturer. Max. ramping rate should not exceed 4°C/Sec.
Soldering Zone	Max. solder temperature should not exceed 260°C. Time within 5°C of actual Max. solder temperature within 3 - 5 seconds. Total time from 25°C room to Max. solder temperature within 5 minutes including Pre-Heating time.
Cooling Zone	Cooling by natural convection in air. Max. ramping down rate should not exceed 6°C/ Sec.



Physical Specifications

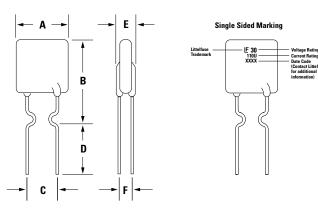
Lead Material	0.90-1.85A: Tin-plated Copper clad steel 2.50-9.00A: Tin-plated Copper
Soldering Characteristics	Solderability per MIL-STD-202, Method 208
Insulating Material	Cured, flame retardant epoxy polymer meets UL94V-0 requirements.
Device Labeling	Marked with 'LF', voltage, current rating, and date code.

Environmental Specifications

Operating Temperature	-40°C to +85°C
Maximum Device Surface Temperature in Tripped State	125°C
Passive Aging	+85°C, 1000 hours -/+5% typical resistance change
Humidity Aging	+85°C, 85% R.H., 1000 hours -/+5% typical resistance change
Thermal Shock	+85°C to -40°C 10 times -/+5% typical resistance change
Solvent Resistance	MIL-STD-202, Method 215 No change
Moisture Resistance Level	Level 1, J-STD-020

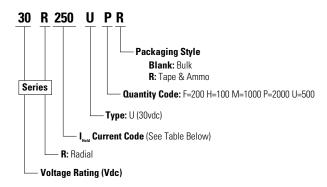


Dimensions & Part Marking System



	А		В	3	С	;	D		E		F		Physica	l Chara	cteristics
Part Number	Inches	mm	Inches	mm	Inches	mm	Inches	mm	Inches	mm	Inches	mm	Lead (dia)	Matarial
Nullibei	Max.	Max.	Max.	Max.	Тур.	Тур.	Min.	Min.	Max.	Max.	Тур.	Тур.	Inches	mm	Material
30R090U	0.29	7.40	0.48	12.20	0.20	5.10	0.30	7.60	0.12	3.00	0.039	1.0	0.02	0.51	Sn/CuFe
30R110U	0.29	7.40	0.56	14.20	0.20	5.10	0.30	7.60	0.12	3.00	0.039	1.0	0.02	0.51	Sn/CuFe
30R135U	0.35	8.90	0.53	13.50	0.20	5.10	0.30	7.60	0.12	3.00	0.039	1.0	0.02	0.51	Sn/CuFe
30R160U	0.35	8.90	0.60	15.20	0.20	5.10	0.30	7.60	0.12	3.00	0.039	1.0	0.02	0.51	Sn/CuFe
30R185U	0.40	10.20	0.62	15.70	0.20	5.10	0.30	7.60	0.12	3.00	0.039	1.0	0.02	0.51	Sn/CuFe
30R250U	0.45	11.40	0.72	18.30	0.20	5.10	0.30	7.60	0.12	3.00	0.039	1.0	0.02	0.51	Sn/Cu
30R300U	0.45	11.40	0.76	19.20	0.20	5.10	0.30	7.60	0.12	3.00	0.047	1.2	0.03	0.81	Sn/Cu
30R400U	0.55	14.00	0.87	22.00	0.20	5.10	0.30	7.60	0.12	3.00	0.047	1.2	0.03	0.81	Sn/Cu
30R500U	0.55	14.00	1.01	25.60	0.40	10.20	0.30	7.60	0.12	3.00	0.047	1.2	0.03	0.81	Sn/Cu
30R600U	0.65	16.50	1.06	26.80	0.40	10.20	0.30	7.60	0.12	3.00	0.047	1.2	0.03	0.81	Sn/Cu
30R700U	0.75	19.10	1.13	28.60	0.40	10.20	0.30	7.60	0.12	3.00	0.047	1.2	0.03	0.81	Sn/Cu
30R800U	0.85	21.60	1.22	31.10	0.40	10.20	0.30	7.60	0.12	3.00	0.047	1.2	0.03	0.81	Sn/Cu
30R900U	0.95	24.10	1.24	31.60	0.40	10.20	0.30	7.60	0.12	3.00	0.047	1.2	0.03	0.81	Sn/Cu

Part Ordering Number System

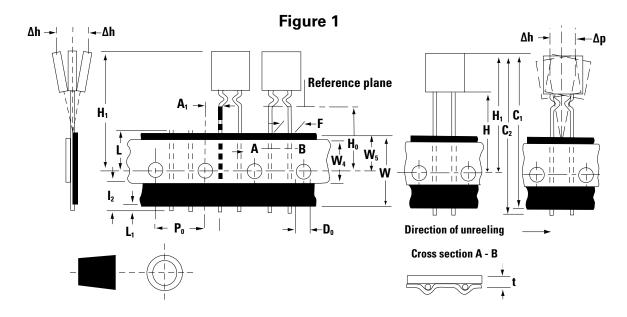




Packaging

Part Number	Ordering Number	I _{hold} (A)	I _{hold} Code	Packaging Option	Quantity	Quantity & Packaging Codes
30R090U	30R090UU 30R090UPR	0.90	090	Bulk Tape and Ammo	500 2000	U PR
30R110U	30R110UU 30R110UPR	1.10	110	Bulk Tape and Ammo	500 2000	U PR
30R135U	30R135UU 30R135UPR	1.35	135	Bulk Tape and Ammo	500 2000	U PR
30R160U	30R160UU 30R160UPR	1.60	160	Bulk Tape and Ammo	500 2000	U
30R185U	30R185UU 30R185UPR	1.85	185	Bulk Tape and Ammo	500 2000	U PR
30R250U	30R250UU 30R250UPR	2.50	250	Bulk Tape and Ammo	500 2000	U PR
30R300U	30R300UU 30R300UPR	3.00	300	Bulk Tape and Ammo	500 2000	U PR
30R400U	30R400UF 30R400UMR	4.00	400	Bulk Tape and Ammo	200 1000	F MR
30R500U	30R500UF 30R500UMR	5.00	500	Bulk Tape and Ammo	200	F MR
30R600U	30R600UF 30R600UMR	6.00	600	Bulk Tape and Ammo	200	F MR
30R700U	30R700UMR	7.00	700	Tape and Ammo	1000	MR
30R800U	30R800UH	8.00	800	Bulk	100	H
30R900U	30R900UH 30R900UMR	9.00 9.00	900 900	Bulk Tape and Ammo	100 1000	H MR

Tape and Ammo Diagram



Tape and Ammo Specifications

Devices taped using EIA468-B/IE286-2 standards. See table below and Figure 1 for details.

Dimension	EIA Mark	IEC Mark	Dimensions			
Differsion	LIA WIAIK	ILC IVIAIR	Dim. (mm)	Tol. (mm)		
Carrier tape width	W	W	18	-0.5 / +1.0		
Hold down tape width:	$W_{_4}$	W _o	11	min.		
Top distance between tape edges	$W_{_{6}}$	W ₂	3	max.		
Sprocket hole position	W_{5}	W ₁	9	-0.5 / +0.75		
Sprocket hole diameter*	D_{o}	D _o	4	-0.32 / +0.2		
Abscissa to plane(straight lead)	Н	Н	18.5	-/+ 3.0		
Abscissa to plane(kinked lead)	H₀	H _o	16	-/+ 0.5		
Abscissa to top: 30R090-30R185	H ₁	H ₁	32.2	max.		
Abscissa to top: 30R250-30R900	-	-	45.0	max.		
Overall width w/o lead protrusion: 30R090-30R185	C ₁	-	42.5	max.		
Overall width w/o lead protrusion: 30R250-30R900	-	-	56	max.		
Overall width w/ lead protrusion: 30R090-30R185	$\mathbf{C_2}$	-	43.2	max.		
Overall width w/ lead protrusion: 30R250-30R900	-	-	57	max.		
Lead protrusion	L ₁	I ₁	1.0	max.		
Protrusion of cut out	L	L	11	max.		
Protrusion beyond hold-down tape	\mathbf{I}_2		Not specified	-		
Sprocket hole pitch: 30R090-30R300	P_{o}	P _o	12.7	-/+ 0.3		
Sprocket hole pitch on: 30R400-30R900	P_{o}	P _o	25.4	-/+ 0.5		
Device pitch: 30R090-30R300	-	-	12.7	-		
Device pitch: 30R400-30R900	-	-	25.4	-		
Pitch tolerance	-	-	20 consecutive.	-/+ 1		
Tape thickness	t	t	0.9	max.		
Tape thickness with splice: 30R090-30R250	t,	-	1.5	max.		
Tape thickness with splice: 30R300-30R900	t,	-	2.0	max.		
Splice sprocket hole alignment	-	-	0	-/+ 0.3		
Body lateral deviation	Δh	Δh	0	-/+ 1.0		
Body tape plane deviation	Δр	Δр	0	-/+ 1.3		
Ordinate to adjacent component lead*	P ₁	P ₁	3.81	-/+ 0.7		
Ordinate to adjacent component lead*	-	-	7.62	-/+ 0.7		
Lead spacing: 30R090-30R400	F	F	5.08	-/+ 0.8		
Lead spacing: 30R500-30R900	F	F	10.18	-/+ 0.8		

Note: *Differs from EIA Specification

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